

Description

The VST10N045 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS(ON)}}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

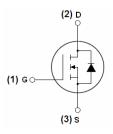
- $V_{DS} = 100V, I_D = 129A$ $R_{DS(ON)} < 5.0 \text{m}\Omega @ V_{GS} = 10V$
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



TO-263



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST10N045-T3	VST10N045	TO-263	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _G s	±20	V	
Drain Current-Continuous	I _D	129	А	
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	92	Α	
Pulsed Drain Current	I _{DM}	480	Α	
Maximum Power Dissipation	P _D	185	W	
Derating factor		1.3	W/℃	
Single pulse avalanche energy (Note 5)	E _{AS}	1000	mJ	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}\!\mathbb{C}$	





Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	ReJC	0.7	°C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA			-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.5		4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =60A	-	4.5	5.0	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =60A	60	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ -50\/\/ -0\/	-	5600	-	PF
Output Capacitance	C _{oss}	V_{DS} =50V, V_{GS} =0V, F=1.0MHz	-	641	-	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0lvinz	-	28	-	PF
Switching Characteristics (Note 4)	·		•			
Turn-on Delay Time	t _{d(on)}		-	16	-	nS
Turn-on Rise Time	t _r	V_{DD} =50 V , I_D =60 A	-	67	-	nS
Turn-Off Delay Time	t _{d(off)}	$V_{GS}\text{=}10V,R_{G}\text{=}4.7\Omega$	-	45	-	nS
Turn-Off Fall Time	t _f		-	14	-	nS
Total Gate Charge	Qg	V -F0V/I -C0A	-	84.7		nC
Gate-Source Charge	Q _{gs}	V_{DS} =50V, I_{D} =60A, V_{GS} =10V	-	30.6		nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	18.3		nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =129A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	129	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S	-	60		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	140		nC

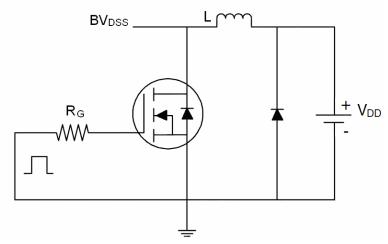
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \leq 10 \; \text{sec.}$
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

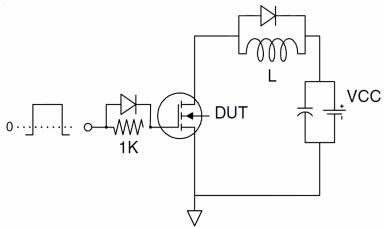


Test Circuit

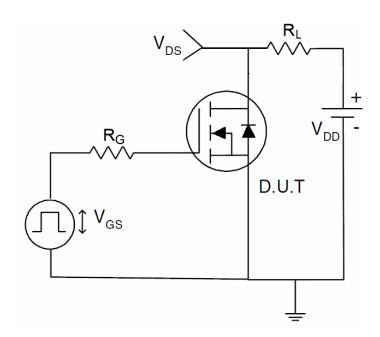
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit







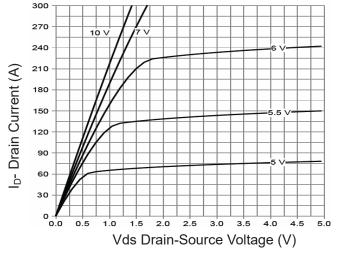


Figure 1 Output Characteristics

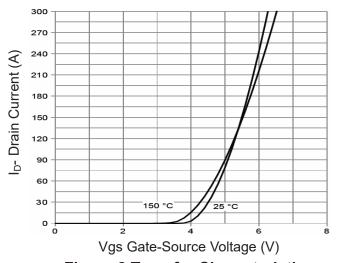


Figure 2 Transfer Characteristics

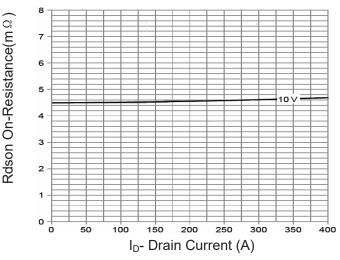


Figure 3 Rdson- Drain Current

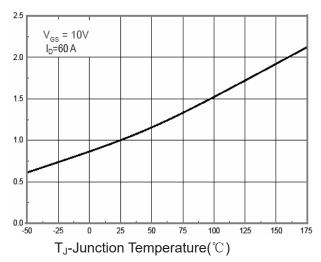


Figure 4 Rdson-JunctionTemperature

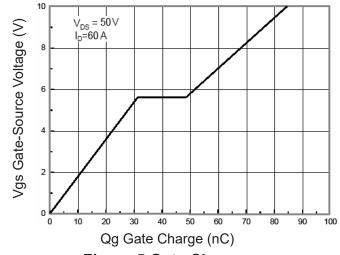


Figure 5 Gate Charge

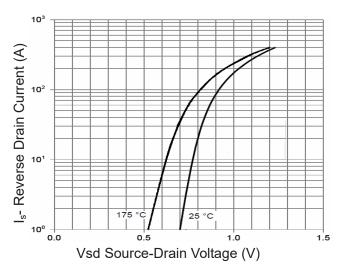


Figure 6 Source- Drain Diode Forward



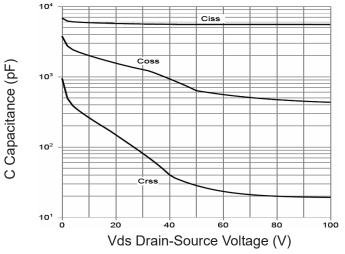
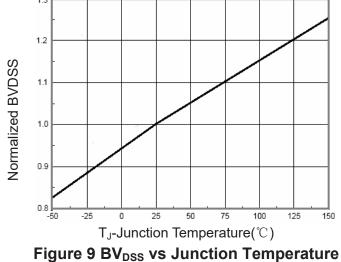


Figure 7 Capacitance vs Vds



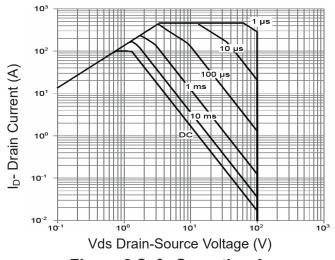


Figure 8 Safe Operation Area

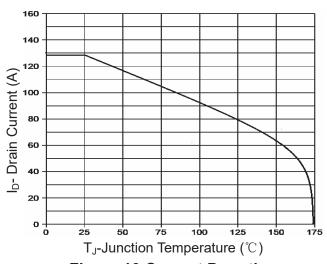


Figure 10 Current De-rating

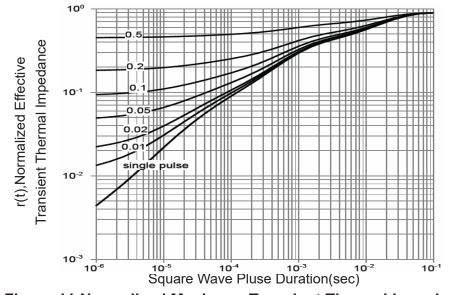


Figure 11 Normalized Maximum Transient Thermal Impedance